

## **SPECIFICATION AMENDMENT**

Please replace the paragraph beginning at page 1, line 6, with the following rewritten paragraph:

-- This application claims the priority benefit of Japanese Patent Application No. 2000-044478, filed February 22, 2000, the entire disclosure of which is incorporated herein by reference. This application is a division of applicant's application Serial No. 10/300,782, filed November 21, 2003, which is a division of applicant's application Serial No. 09/782,153 09/782,163, filed February 14, 2001. --

Please replace the paragraph beginning at page 5, line 14, with the following rewritten paragraph:

--The invention will be more particularly described with reference to the accompanying drawings in which:

Fig. 1 is a plan view of a semiconductor device having surplus resin, which is formed by a molding apparatus of a first embodiment of the invention;

Fig. 2 is a side sectional view taken on line A-A' of Fig. 1;

Figs. 3A through 3D are sequential sectional views of a method for encapsulating a semiconductor chip with resin using the molding apparatus of Figs. 1 and 2;

Figs. 4A through [[4D]] 4C are sequential sectional views showing a method for detaching surplus resin;

Fig. 5A is a plan view of a semiconductor device having surplus resin, which is formed by a molding apparatus of a second embodiment of the invention;

Fig. 5B is a side sectional view taken on line B-B' of Fig. 5A;  
Figs. 6A through 6D are sequential sectional views of a method for  
encapsulating a semiconductor chip with resin using conventional molding  
apparatus; and

Figs. 7A through 7D are plan views of semiconductor devices, each  
having residual burrs of surplus resin.--